AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

1. (Currently Amended) A polyimide metal laminate comprising a copper foil and a stainless steel foil or stainless steel foils formed on both sides of a polyimide resin, wherein the polyimide resin which comes in contact with the stainless steel foil or the copper foil has a heat resistance temperature being not less than 350°C, a coefficient of humidity expansion at 32°C being from 1 to 20 ppm/%RH, an average value of the etching rate by a 50 wt % aqueous solution of potassium hydroxide at 80°C being not less than 1.0 μm/min, and a peel strength after heating at 350°C for 60 minutes being not less than 1.0 kN/m,

wherein the polyimide resin is a thermoplastic polyimide obtained by reacting a diamine with a tetracarboxylic acid dianhydride, the tetracarboxylic acid dianhydride in use is obtained by combining at least one kind of tetracarboxylic acid dianhydride selected from pyromellitic acid dianhydride, p-phenylene bis(trimellitic acid monoester anhydride), 3,3',4,4'-ethylene glycol dibenzoate tetracarboxylic acid dianhydride and 2,2-bis(4-hydroxyphenyl)propane-3,3',4,4'-benzophenone tetracarboxylic acid dianhydride with 3,3',4,4'-benzophenone tetracarboxylic acid dianhydride, and 3,3',4,4'-benzophenone tetracarboxylic acid dianhydride, and not more than 50 mole % of the total tetracarboxylic acid dianhydride in use, and pyromellitic acid dianhydride is not less than 50 mole % of the total tetracarboxylic acid dianhydride in use.

2-3. (Canceled)

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- 4. (Original) The polyimide metal laminate according to claim 1, wherein the polyimide resin which comes in contact with the stainless steel foil or the copper foil is a thermoplastic polyimide obtained by reacting a diamine with a tetracarboxylic acid dianhydride, and comprises at least one kind of diamine selected from 1,3-bis(3-aminophenoxy)benzene, 4,4'-bis(3-aminophenoxy)biphenyl, 3,3'-diaminobenzophenone and 1,3-bis(3-(3-aminophenoxy)phenoxy)benzene as a diamine in use.
- 5. (Previously Presented) A suspension for a hard disk drive prepared from the polyimide metal laminate as described in claim 4.
 - 6-7. (Canceled)
- 8. (Previously Presented) A suspension for a hard disk drive prepared from the polyimide metal laminate as described in claim 1.